



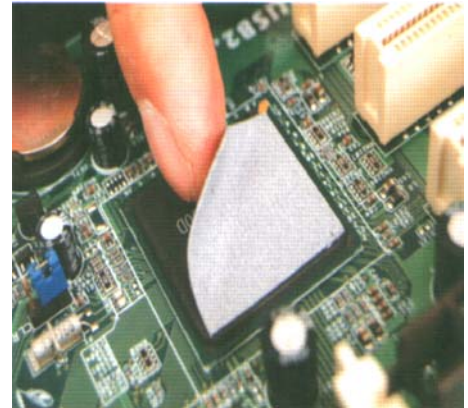
THERMAL INTERFACE PAD: THEA708F

Characteristic

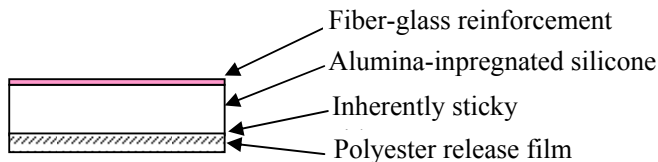
This product is made of soft and highly conformable, low modulus silicone polymer filled with Alumina filler that makes it an excellent heat conductor. Fiber glass top layer makes handling easy and holds the shape of this soft pad in check.

Application

- Suitable as thermal interface pad where pressure load on the components or PCB is critical.
- Available in custom sizes and die-cut shapes/sizes



Product Structure



Technical data

ITEM		VALUE	TEST METHOD	
Material	Binder	Silicone		
	Filler	Alumina		
	Liner	Polyester		
Mechanical properties	Thickness (mm)	Silicone pad available	0.5 to 15 ±0.25	ASTM D 1000
		Fiber glass layer	0.012	
		Release liner	To be disposed of	
	Standard size (mm)		250 x 250	
	Color	Silicone pad	Dark Gray	Visual
		Fiber glass layer	Pink	Visual
		Release film	Transparent	Visual
Hardness (Shore 00)		40	ASTM D 2240	
Specific gravity (g/cm ³)		2.0 ~ 2.2	ASTM D 792	
Continuous usage temp. (°C)		-60 ~ +200		
Electrical properties	Dielectric constant		5.5 ±0.5	ASTM D 150
	Dielectric breakdown (kV AC)		> 10	ASTM D 149
	Volume resistivity (ohm-meter)		> 10 ¹²	ASTM D 257
Thermal conductivity 10psi (w/mK)		0.8	ASTM D 5470	
Flame Rating		UL94 V0		